

Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

E·XFI

Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	30 MIPs
Connectivity	I ² C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	20
Program Memory Size	24KB (8K x 24)
Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	A/D 10x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic30f3013t-30i-so

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Pin Diagrams



NOTES:

2.4.2.4 Data Space Write Saturation

In addition to adder/subtracter saturation, writes to data space may also be saturated but without affecting the contents of the source accumulator. The data space write saturation logic block accepts a 16-bit, 1.15 fractional value from the round logic block as its input, together with overflow status from the original source (accumulator) and the 16-bit round adder. These are combined and used to select the appropriate 1.15 fractional value as output to write to data space memory.

If the SATDW bit in the CORCON register is set, data (after rounding or truncation) is tested for overflow and adjusted accordingly. For input data greater than 0x007FFF, data written to memory is forced to the maximum positive 1.15 value, 0x7FFF. For input data less than 0xFF8000, data written to memory is forced to the maximum negative 1.15 value, 0x8000. The MSb of the source (bit 39) is used to determine the sign of the operand being tested.

If the SATDW bit in the CORCON register is not set, the input data is always passed through unmodified under all conditions.

2.4.3 BARREL SHIFTER

The barrel shifter is capable of performing up to 16-bit arithmetic or logic right shifts, or up to 16-bit left shifts in a single cycle. The source can be either of the two DSP accumulators, or the X bus (to support multi-bit shifts of register or memory data).

The shifter requires a signed binary value to determine both the magnitude (number of bits) and direction of the shift operation. A positive value shifts the operand right. A negative value shifts the operand left. A value of '0' does not modify the operand.

The barrel shifter is 40 bits wide, thereby obtaining a 40-bit result for DSP shift operations and a 16-bit result for MCU shift operations. Data from the X bus is presented to the barrel shifter between bit positions 16 to 31 for right shifts, and bit positions 0 to 16 for left shifts.

3.1.1 DATA ACCESS FROM PROGRAM MEMORY USING TABLE INSTRUCTIONS

This architecture fetches 24-bit wide program memory. Consequently, instructions are always aligned. However, as the architecture is modified Harvard, data can also be present in program space.

There are two methods by which program space can be accessed: via special table instructions, or through the remapping of a 16K word program space page into the upper half of data space (see Section 3.1.2 "Data Access from Program Memory Using Program Space Visibility"). The TBLRDL and TBLWTL instructions offer a direct method of reading or writing the lsw of any address within program space, without going through data space. The TBLRDH and TBLWTH instructions are the only method whereby the upper 8 bits of a program space word can be accessed as data.

The PC is incremented by two for each successive 24-bit program word. This allows program memory addresses to directly map to data space addresses. Program memory can thus be regarded as two 16-bit word wide address spaces, residing side by side, each with the same address range. TBLRDL and TBLWTL access the space which contains the lsw, and TBLRDH and TBLWTH access the space which contains the MSB.

Figure 3-2 shows how the EA is created for table operations and data space accesses (PSV = 1). Here, P<23:0> refers to a program space word, whereas D<15:0> refers to a data space word.

A set of table instructions are provided to move byte or word-sized data to and from program space. See Figure 3-4 and Figure 3-5.

 TBLRDL: Table Read Low Word: Read the LS Word of the program address; P<15:0> maps to D<15:0>. Byte: Read one of the LSB of the program

address; P < 7:0 > maps to the destination byte when byte select = 0;

P<15:8> maps to the destination byte when byte select = 1.

- TBLWTL: Table Write Low (refer to Section 5.0 "Flash Program Memory" for details on Flash Programming)
- TBLRDH: Table Read High Word: Read the MS Word of the program address; P<23:16> maps to D<7:0>; D<15:8> will always be = 0.

Byte: Read one of the MSB of the program address;

P<23:16> maps to the destination byte when byte select = 0;

The destination byte will always be = 0 when byte select = 1.

 TBLWTH: Table Write High (refer to Section 5.0 "Flash Program Memory" for details on Flash Programming)

FIGURE 3-3: PROGRAM DATA TABLE ACCESS (Isw)





NOTES:

TABLE 10-1: TIMER2/3 REGISTER MAP

0
20
10
Ň
cro
ch
Ð
Te
h
<u>l</u> o
go
~
ıc.

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset State
TMR2	0106	Timer2 Register															uuuu uuuu uuuu	
TMR3HLD	0108		Timer3 Holding Register (for 32-bit timer operations only)												uuuu uuuu uuuu uuuu			
TMR3	010A		Timer3 Register											uuuu uuuu uuuu uuuu				
PR2	010C								Pe	riod Registe	r 2							1111 1111 1111 1111
PR3	010E								Pe	riod Registe	r 3							1111 1111 1111 1111
T2CON	0110	TON		TSIDL			—	—	-	—	TGATE	TCKPS1	TCKPS0	T32		TCS	_	0000 0000 0000 0000
T3CON	0112	TON	_	TSIDL	_	_	_	_	_	_	TGATE	TCKPS1	TCKPS0	_	_	TCS	_	0000 0000 0000 0000

Legend: u = uninitialized bit; — = unimplemented bit, read as '0'

Note: Refer to the "dsPIC30F Family Reference Manual" (DS70046) for descriptions of register bit fields.

11.0 INPUT CAPTURE MODULE

Note: This data sheet summarizes features of this group of dsPIC30F devices and is not intended to be a complete reference source. For more information on the CPU, peripherals, register descriptions and general device functionality, refer to the "dsPIC30F Family Reference Manual" (DS70046).

This section describes the input capture module and associated operational modes. The features provided by this module are useful in applications requiring frequency (period) and pulse measurement.

Figure 11-1 depicts a block diagram of the input capture module. Input capture is useful for such modes as:

- Frequency/Period/Pulse Measurements
- · Additional Sources of External Interrupts

Important operational features of the input capture module are:

- Simple Capture Event mode
- Timer2 and Timer3 mode selection
- · Interrupt on input capture event

These operating modes are determined by setting the appropriate bits in the IC1CON and IC2CON registers. The dsPIC30F2011/2012/3012/3013 devices have two capture channels.

11.1 Simple Capture Event Mode

The simple capture events in the dsPIC30F product family are:

- · Capture every falling edge
- Capture every rising edge
- Capture every 4th rising edge
- · Capture every 16th rising edge
- · Capture every rising and falling edge

These simple Input Capture modes are configured by setting the appropriate bits, ICM<2:0> (ICxCON<2:0>).

11.1.1 CAPTURE PRESCALER

There are four input capture prescaler settings specified by bits ICM<2:0> (ICxCON<2:0>). Whenever the capture channel is turned off, the prescaler counter is cleared. In addition, any Reset clears the prescaler counter.

FIGURE 11-1: INPUT CAPTURE MODE BLOCK DIAGRAM⁽¹⁾



16.1 A/D Result Buffer

The module contains a 16-word dual port read-only buffer, called ADCBUF0...ADCBUFF, to buffer the A/D results. The RAM is 12 bits wide but the data obtained is represented in one of four different 16-bit data formats. The contents of the sixteen A/D Conversion Result Buffer registers, ADCBUF0 through ADCBUFF, cannot be written by user software.

16.2 Conversion Operation

After the ADC module has been configured, the sample acquisition is started by setting the SAMP bit. Various sources, such as a programmable bit, timer time-outs and external events, will terminate acquisition and start a conversion. When the A/D conversion is complete, the result is loaded into ADCBUF0...ADCBUFF, and the DONE bit and the A/D interrupt flag, ADIF, are set after the number of samples specified by the SMPI bit. The ADC module can be configured for different interrupt rates as described in Section 16.3 "Selecting the Conversion Sequence".

The following steps should be followed for doing an A/D conversion:

- 1. Configure the ADC module:
 - Configure analog pins, voltage reference and digital I/O
 - Select A/D input channels
 - Select A/D conversion clock
 - Select A/D conversion trigger
 - Turn on ADC module
- 2. Configure A/D interrupt (if required):
 - Clear ADIF bit
 - Select A/D interrupt priority
- 3. Start sampling
- 4. Wait the required acquisition time
- 5. Trigger acquisition end, start conversion
- 6. Wait for A/D conversion to complete, by either:
 - Waiting for the A/D interrupt, or
 - Waiting for the DONE bit to get set
- 7. Read A/D result buffer; clear ADIF if required

16.3 Selecting the Conversion Sequence

Several groups of control bits select the sequence in which the A/D connects inputs to the sample/hold channel, converts a channel, writes the buffer memory and generates interrupts.

The sequence is controlled by the sampling clocks.

The SMPI bits select the number of acquisition/conversion sequences that would be performed before an interrupt occurs. This can vary from 1 sample per interrupt to 16 samples per interrupt.

The BUFM bit will split the 16-word results buffer into two 8-word groups. Writing to the 8-word buffers will be alternated on each interrupt event.

Use of the BUFM bit will depend on how much time is available for the moving of the buffers after the interrupt.

If the processor can quickly unload a full buffer within the time it takes to acquire and convert one channel, the BUFM bit can be '0' and up to 16 conversions (corresponding to the 16 input channels) may be done per interrupt. The processor will have one acquisition and conversion time to move the sixteen conversions.

If the processor cannot unload the buffer within the acquisition and conversion time, the BUFM bit should be '1'. For example, if SMPI<3:0> (ADCON2<5:2>) = 0111, then eight conversions will be loaded into 1/2 of the buffer, following which an interrupt occurs. The next eight conversions will be loaded into the other 1/2 of the buffer. The processor will have the entire time between interrupts to move the eight conversions.

The ALTS bit can be used to alternate the inputs selected during the sampling sequence. The input multiplexer has two sets of sample inputs: MUX A and MUX B. If the ALTS bit is '0', only the MUX A inputs are selected for sampling. If the ALTS bit is '1' and SMPI<3:0> = 0000 on the first sample/convert sequence, the MUX A inputs are selected and on the next acquire/convert sequence, the MUX B inputs are selected.

The CSCNA bit (ADCON2<10>) will allow the multiplexer input to be alternately scanned across a selected number of analog inputs for the MUX A group. The inputs are selected by the ADCSSL register. If a particular bit in the ADCSSL register is '1', the corresponding input is selected. The inputs are always scanned from lower to higher numbered inputs, starting after each interrupt. If the number of inputs selected is greater than the number of samples taken per interrupt, the higher numbered inputs are unused.

TABLE 16-2: A/D CONVERTER REGISTER MAP FOR dsPIC30F2011/3012	TABLE 16-2:	A/D CONVERTER	REGISTER MAP	FOR dsPIC30F2011/3012
--	-------------	---------------	---------------------	-----------------------

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset State
ADCBUF0	0280	_	_	_	—		ADC Data Buffer 0 0										0000 uuuu uuuu uuuu	
ADCBUF1	0282				—		ADC Data Buffer 1										0000 uuuu uuuu uuuu	
ADCBUF2	0284				—						ADC Dat	ta Buffer 2						0000 uuuu uuuu uuuu
ADCBUF3	0286				—						ADC Dat	ta Buffer 3						0000 uuuu uuuu uuuu
ADCBUF4	0288				—						ADC Dat	ta Buffer 4						0000 uuuu uuuu uuuu
ADCBUF5	028A				—						ADC Dat	ta Buffer 5						0000 uuuu uuuu uuuu
ADCBUF6	028C				—						ADC Dat	ta Buffer 6	;					0000 uuuu uuuu uuuu
ADCBUF7	028E				—						ADC Dat	ta Buffer 7	,					0000 uuuu uuuu uuuu
ADCBUF8	0290				—						ADC Dat	ta Buffer 8						0000 uuuu uuuu uuuu
ADCBUF9	0292				—						ADC Dat	ta Buffer 9)					0000 uuuu uuuu uuuu
ADCBUFA	0294				—						ADC Data	a Buffer 10	C					0000 uuuu uuuu uuuu
ADCBUFB	0296				—						ADC Dat	a Buffer 1'	1					0000 uuuu uuuu uuuu
ADCBUFC	0298				—						ADC Data	a Buffer 12	2					0000 uuuu uuuu uuuu
ADCBUFD	029A				—						ADC Data	a Buffer 13	3					0000 uuuu uuuu uuuu
ADCBUFE	029C				—						ADC Data	a Buffer 1₄	4					0000 uuuu uuuu uuuu
ADCBUFF	029E				—						ADC Data	a Buffer 15	5					0000 uuuu uuuu uuuu
ADCON1	02A0	ADON		ADSIDL	—			FORM	1<1:0>	5	SRC<2:0	>		—	ASAM	SAMP	DONE	0000 0000 0000 0000
ADCON2	02A2	V	/CFG<2:0>	>	—		- CSCNA BUFS - SMPI<3:0> BUFM ALTS C							0000 0000 0000 0000				
ADCON3	02A4	_	_	_		SAMC<4:0> ADRC - ADCS<5:0> (0000 0000 0000 0000				
ADCHS	02A6	—	—	_	CH0NB	CH0SB<3:0> — — CH0NA CH0SA<3:0> 0							0000 0000 0000 0000					
ADPCFG	02A8	_	_	_	_	_	PCFG7_PCFG6_PCFG5_PCFG4_PCFG3_PCF				PCFG2	PCFG1	PCFG0	0000 0000 0000 0000				
ADCSSL	02AA	_	_	_	_		_	_	_	CSSL7	CSSL6	CSSL5	CSSL4	CSSL3	CSSL2	CSSL1	CSSL0	0000 0000 0000 0000

Legend: u = uninitialized bit; — = unimplemented bit, read as '0'

Note: Refer to the "dsPIC30F Family Reference Manual" (DS70046) for descriptions of register bit fields.

17.2.3 LP OSCILLATOR CONTROL

Enabling the LP oscillator is controlled with two elements:

- The current oscillator group bits COSC<2:0>.
- The LPOSCEN bit (OSCCON register).

The LP oscillator is on (even during Sleep mode) if LPOSCEN = 1. The LP oscillator is the device clock if:

- COSC<2:0> = 000 (LP selected as main osc.) and
- LPOSCEN = 1

Keeping the LP oscillator on at all times allows for a fast switch to the 32 kHz system clock for lower power operation. Returning to the faster main oscillator will still require a start-up time

17.2.4 PHASE LOCKED LOOP (PLL)

The PLL multiplies the clock which is generated by the primary oscillator or Fast RC oscillator. The PLL is selectable to have either gains of x4, x8, and x16. Input and output frequency ranges are summarized in Table 17-3.

TABLE 17-3: PLL FREQUENCY RANGE

Fin	PLL Multiplier	Fout
4 MHz-10 MHz	x4	16 MHz-40 MHz
4 MHz-10 MHz	x8	32 MHz-80 MHz
4 MHz-7.5 MHz	x16	64 MHz-120 MHz

The PLL features a lock output which is asserted when the PLL enters a phase locked state. Should the loop fall out of lock (e.g., due to noise), the lock signal will be rescinded. The state of this signal is reflected in the read-only LOCK bit in the OSCCON register.

17.2.5 FAST RC OSCILLATOR (FRC)

The FRC oscillator is a fast (7.37 MHz $\pm 2\%$ nominal) internal RC oscillator. This oscillator is intended to provide reasonable device operating speeds without the use of an external crystal, ceramic resonator, or RC network. The FRC oscillator can be used with the PLL to obtain higher clock frequencies.

The dsPIC30F operates from the FRC oscillator whenever the current oscillator selection control bits in the OSCCON register (OSCCON<14:12>) are set to '001'.

The four bit field specified by TUN<3:0> (OSCTUN <3:0>) allows the user to tune the internal fast RC oscillator (nominal 7.37 MHz). The user can tune the FRC oscillator within a range of +10.5% (840 kHz) and -12% (960 kHz) in steps of 1.50% around the factory calibrated setting, as shown in Table 17-4.

Note: OSCTUN functionality has been provided to help customers compensate for temperature effects on the FRC frequency over a wide range of temperatures. The tuning step size is an approximation and is neither characterized nor tested. If OSCCON<14:12> are set to '111' and FPR<4:0> are set to '00001', '01010' or '00011', a PLL multiplier of 4, 8 or 16 (respectively) is applied.

Note:	When a 16x PLL is used, the FRC fre-
	quency must not be tuned to a frequency
	greater than 7.5 MHz.

TABLE 17-4: FRC TUNING

TUN<3:0> Bits	FRC Frequency
0111	+ 10.5%
0110	+ 9.0%
0101	+ 7.5%
0100	+ 6.0%
0011	+ 4.5%
0010	+ 3.0%
0001	+ 1.5%
0000	Center Frequency (oscillator is
	running at calibrated frequency)
1111	- 1.5%
1110	- 3.0%
1101	- 4.5%
1100	- 6.0%
1011	- 7.5%
1010	- 9.0%
1001	- 10.5%
1000	- 12.0%

17.2.6 LOW-POWER RC OSCILLATOR (LPRC)

The LPRC oscillator is a component of the Watchdog Timer (WDT) and oscillates at a nominal frequency of 512 kHz. The LPRC oscillator is the clock source for the Power-up Timer (PWRT) circuit, WDT and clock monitor circuits. It may also be used to provide a low-frequency clock source option for applications where power consumption is critical and timing accuracy is not required.

The LPRC oscillator is always enabled at a Power-on Reset because it is the clock source for the PWRT. After the PWRT expires, the LPRC oscillator will remain on if one of the following is true:

- The Fail-Safe Clock Monitor is enabled
- The WDT is enabled
- The LPRC oscillator is selected as the system clock via the COSC<2:0> control bits in the OSCCON register

If one of the above conditions is not true, the LPRC will shut-off after the PWRT expires.

Note 1:	OSC2 pin	function is	determin	ed by the
	Primary	Oscillator	mode	selection
	(FPR<4:0>	>).		

 OSC1 pin cannot be used as an I/O pin even if the secondary oscillator or an internal clock source is selected at all times.

17.2.7 FAIL-SAFE CLOCK MONITOR

The Fail-Safe Clock Monitor (FSCM) allows the device to continue to operate even in the event of an oscillator failure. The FSCM function is enabled by appropriately programming the FCKSM Configuration bits (clock switch and monitor selection bits) in the FOSC Device Configuration register. If the FSCM function is enabled, the LPRC internal oscillator will run at all times (except during Sleep mode) and will not be subject to control by the SWDTEN bit.

In the event of an oscillator failure, the FSCM will generate a clock failure trap event and will switch the system clock over to the FRC oscillator. The user will then have the option to either attempt to restart the oscillator or execute a controlled shutdown. The user may decide to treat the trap as a warm Reset by simply loading the Reset address into the oscillator fail trap vector. In this event, the CF (Clock Fail) bit (OSCCON<3>) is also set whenever a clock failure is recognized.

In the event of a clock failure, the WDT is unaffected and continues to run on the LPRC clock.

If the oscillator has a very slow start-up time coming out of POR, BOR or Sleep, it is possible that the PWRT timer will expire before the oscillator has started. In such cases, the FSCM will be activated and the FSCM will initiate a clock failure trap, and the COSC<2:0> bits are loaded with FRC oscillator selection. This will effectively shut-off the original oscillator that was trying to start.

The user may detect this situation and restart the oscillator in the clock fail trap ISR.

Upon a clock failure detection, the FSCM module will initiate a clock switch to the FRC oscillator as follows:

- 1. The COSC bits (OSCCON<14:12>) are loaded with the FRC oscillator selection value.
- 2. CF bit is set (OSCCON<3>).
- 3. OSWEN control bit (OSCCON<0>) is cleared.

For the purpose of clock switching, the clock sources are sectioned into four groups:

- Primary (with or without PLL)
- Secondary
- Internal FRC
- Internal LPRC

The user can switch between these functional groups but cannot switch between options within a group. If the primary group is selected, then the choice within the group is always determined by the FPR<4:0> Configuration bits. The OSCCON register holds the Control and Status bits related to clock switching.

- COSC<2:0>: Read-only bits always reflect the current oscillator group in effect.
- NOSC<2:0>: Control bits which are written to indicate the new oscillator group of choice.
 - On POR and BOR, COSC<2:0> and NOSC<2:0> are both loaded with the Configuration bit values FOS<2:0>.
- LOCK: The LOCK bit indicates a PLL lock.
- CF: Read-only bit indicating if a clock fail detect has occurred.
- OSWEN: Control bit changes from a '0' to a '1' when a clock transition sequence is initiated. Clearing the OSWEN control bit will abort a clock transition in progress (used for hang-up situations).

If Configuration bits FCKSM<1:0> = 1x, then the clock switching and Fail-Safe Clock monitoring functions are disabled. This is the default Configuration bit setting.

If clock switching is disabled, then the FOS<2:0> and FPR<4:0> bits directly control the oscillator selection and the COSC<2:0> bits do not control the clock selection. However, these bits will reflect the clock source selection.

Note: The application should not attempt to switch to a clock of frequency lower than 100 kHz when the Fail-Safe Clock Monitor is enabled. If such clock switching is performed, the device may generate an oscillator fail trap and switch to the Fast RC oscillator.

17.2.8 PROTECTION AGAINST ACCIDENTAL WRITES TO OSCCON

A write to the OSCCON register is intentionally made difficult because it controls clock switching and clock scaling.

To write to the OSCCON low byte, the following code sequence must be executed without any other instructions in between:

Byte Write 0x46 to OSCCON low Byte Write 0x57 to OSCCON low

Byte write is allowed for one instruction cycle. Write the desired value or use bit manipulation instruction.

To write to the OSCCON high byte, the following instructions must be executed without any other instructions in between:

Byte Write 0x78 to OSCCON high Byte Write 0x9A to OSCCON high

Byte write is allowed for one instruction cycle. Write the desired value or use bit manipulation instruction.

TABLE 17-7: SYSTEM INTEGRATION REGISTER MAP

SFR Name	Address	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset State
RCON	0740	TRAPR	IOPUWR	BGST	LVDEN		LVD	_<3:0>		EXTR	SWR	SWDTEN	WDTO	SLEEP	IDLE	BOR	POR	(Note 1)
OSCCON	0742	_	CC	DSC<2:0	>	—	1	NOSC<2:()>	POS	T<1:0>	LOCK	—	CF		LPOSCEN	OSWEN	(Note 2)
OSCTUN	0744	_	_	—	—	—	-	_	_	_	_	_	—	TUN3	TUN2	TUN1	TUN0	(Note 2)
PMD1	0770	_	_	T3MD	T2MD	T1MD	-	_	_	I2CMD	U2MD ⁽³⁾	U1MD	—	SPI1MD		_	ADCMD	0000 0000 0000 0000
PMD2	0772	_	_	_	_	_	_	IC2MD	IC1MD	_	_	_	_	_	_	OC2MD	OC1MD	0000 0000 0000 0000

Legend: — = unimplemented bit, read as '0'

Note 1: Reset state depends on type of reset.

2: Reset state depends on Configuration bits.

3: Only available on dsPIC30F3013 devices.

TABLE 17-8: DEVICE CONFIGURATION REGISTER MAP

Name	Address	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
FOSC	F80000	FCKSM	1<1:0>	—	—	_		FOS<2:0>		—	_	—		FPR<4:0>			
FWDT	F80002	FWDTEN	_	_	_	_	_	_	_	_	_	FWPS	A<1:0>	FWPSB<3:0>			
FBORPOR	F80004	MCLREN	_	_	_	_	PWMPIN ⁽¹⁾	HPOL ⁽¹⁾	LPOL ⁽¹⁾	BOREN	_	BOR\	/<1:0>	_	_	FPWR	Г<1:0>
FBS	F80006	_	_	Reser	rved(2)	_	_	_	Reserved ⁽²⁾	_	_	_	_		Reserv	ed ⁽²⁾	
FSS	F80008	_	_	Reser	rved(2)	_	_	Res	erved ⁽²⁾	_	_	_	_	Reserved ⁽²⁾			
FGS	F8000A	_	_	_	_	_	_	_	_	_	_	_	_	_	Reserved ⁽³⁾	GCP	GWRP
FICD	F8000C	BKBUG	COE	_	_	_	_	_	_	_	_	_	_	_	_	ICS<	1:0>

Legend: — = unimplemented bit, read as '0'

Note 1: These bits are reserved (read as '1' and must be programmed as '1').

2: Reserved bits read as '1' and must be programmed as '1'.

3: The FGS<2> bit is a read-only copy of the GCP bit (FGS<1>).

20.1 DC Characteristics

TABLE 20-1: OPERATING MIPS VS. VOLTAGE

Voo Banga	Tomp Bongo	Max MIPS							
VDD Kalige		dsPIC30FXXX-30I	dsPIC30FXXX-20E						
4.5-5.5V	-40°C to 85°C	30	—						
4.5-5.5V	-40°C to 125°C	—	20						
3.0-3.6V	-40°C to 85°C	20	—						
3.0-3.6V	-40°C to 125°C	—	15						
2.5-3.0V	-40°C to 85°C	10	—						

TABLE 20-2: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min	Тур	Max	Unit	
dsPIC30F201x-30I						
dsPIC30F301x-30I						
Operating Junction Temperature Range	TJ	-40	—	+125	°C	
Operating Ambient Temperature Range	TA	-40	—	+85	°C	
dsPIC30F201x-20E						
dsPIC30F301x-20E						
Operating Junction Temperature Range	TJ	-40	—	+150	°C	
Operating Ambient Temperature Range	TA	-40	—	+125	°C	
Power Dissipation:						
Internal chip power dissipation:						
$P_{INT} = V_{DD} \times (I_{DD} - \Sigma I_{OH})$	PD	PD PINT + PI/O			W	
I/O Pin power dissipation:						
$\mathbf{P}_{\mathrm{I/O}} = \Sigma \left(\{ \mathbf{V}_{\mathrm{DD}} - \mathbf{V}_{\mathrm{OH}} \} \times \mathbf{I}_{\mathrm{OH}} \right) + \Sigma \left(\mathbf{V}_{\mathrm{OL}} \times \mathbf{I}_{\mathrm{OL}} \right)$						
Maximum Allowed Power Dissipation	PDMAX	1АХ (ТЈ - ТА) / θЈА				

TABLE 20-3: THERMAL PACKAGING CHARACTERISTICS

Characteristic	Symbol	Тур	Max	Unit	Notes
Package Thermal Resistance, 18-pin PDIP (P)	θJA	44		°C/W	1
Package Thermal Resistance, 18-pin SOIC (SO)	θJA	57		°C/W	1
Package Thermal Resistance, 28-pin SPDIP (SP)	θJA	42	-	°C/W	1
Package Thermal Resistance, 28-pin (SOIC)	θJA	49		°C/W	1
Package Thermal Resistance, 44-pin QFN	θJA	28	_	°C/W	1

Note 1: Junction to ambient thermal resistance, Theta-ja (θ JA) numbers are achieved by package simulations.

			Standard O	andard Operating Conditions: 2.5V to 5.5V					
DC CHARACT	ERISTICS		(unless otherwise stated)						
			Operating te	-40°C \leq IA \leq +85°C for Industrial -40°C \leq TA \leq +125°C for Extended					
Parameter No.	Typical ⁽¹⁾	Max	Units		Conditions				
Operating Cur	rent (IDD) ⁽²⁾								
DC51a	1.3	2.5	mA	25°C					
DC51b	1.3	2.5	mA	85°C	3.3V				
DC51c	1.2	2.5	mA	125°C		0.128 MIPS			
DC51e	3.2	5.0	mA	25°C		LPRC (512 kHz)			
DC51f	2.9	5.0	mA	85°C	5V				
DC51g	2.8	5.0	mA	125°C					
DC50a	3.0	5.0	mA	25°C					
DC50b	3.0	5.0	mA	85°C	3.3V				
DC50c	3.0	5.0	mA	125°C		(1.8 MIPS)			
DC50e	6.0	9.0	mA	25°C		FRC (7.37 MHz)			
DC50f	5.8	9.0	mA	85°C	5V				
DC50g	5.7	9.0	mA	125°C					
DC43a	5.2	8.0	mA	25°C					
DC43b	5.3	8.0	mA	85°C	3.3V				
DC43c	5.4	8.0	mA	125°C					
DC43e	9.7	15.0	mA	25°C		4 MIFS			
DC43f	9.6	15.0	mA	85°C	5V				
DC43g	9.5	15.0	mA	125°C					
DC44a	11.0	17.0	mA	25°C					
DC44b	11.0	17.0	mA	85°C	3.3V				
DC44c	11.0	17.0	mA	125°C					
DC44e	19.0	29.0	mA	25°C		TO MIPS			
DC44f	19.0	29.0	mA	85°C	5V				
DC44g	20.0	30.0	mA	125°C					
DC47a	20.0	35.0	mA	25°C	2.2\/				
DC47b	21.0	35.0	mA	85°C	3.3V				
DC47d	35.0	50.0	mA	25°C		20 MIPS			
DC47e	36.0	50.0	mA	85°C	5V				
DC47f	36.0	50.0	mA	125°C					
DC49a	51.0	70.0	mA	25°C	5\/				
DC49b	51.0	70.0	mA	85°C	50				

TABLE 20-6: DC CHARACTERISTICS: IDLE CURRENT (IIDLE)

Note 1: Data in "Typical" column is at 5V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: Base IIDLE current is measured with Core off, Clock on and all modules turned off.

TABLE 20-15: PLL CLOCK TIMING SPECIFICATIONS (VDD = 2.5 TO 5.5 V)

AC CHA	RACTERI	STICS	Standard Operating Conditions: 2.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended						
Param No.	Symbol	Characterist	ic ⁽¹⁾	c ⁽¹⁾ Min Typ ⁽²⁾ Max Units Conditions					
OS50	Fplli	PLL Input Frequency	/ Range ⁽²⁾	4		10	MHz	EC with 4x PLL	
				4	—	10	MHz	EC with 8x PLL	
				4	—	7.5 ⁽⁴⁾	MHz	EC with 16x PLL	
				4	—	10	MHz	XT with 4x PLL	
				4	—	10	MHz	XT with 8x PLL	
				4	—	7.5 ⁽⁴⁾	MHz	XT with 16x PLL	
				5 ⁽³⁾	—	10	MHz	HS/2 with 4x PLL	
				5 ⁽³⁾	—	10	MHz	HS/2 with 8x PLL	
				5 ⁽³⁾	—	7.5 ⁽⁴⁾	MHz	HS/2 with 16x PLL	
				4	—	8.33 ⁽³⁾	MHz	HS/3 with 4x PLL	
			4 — 8.33 ⁽³⁾ MHz HS/3 with 8x PLL					HS/3 with 8x PLL	
				4	—	7.5 ⁽⁴⁾	MHz	HS/3 with 16x PLL	
OS51	Fsys	On-Chip PLL Output	(2)	16		120	MHz	EC, XT, HS/2, HS/3 modes with PLL	
OS52	TLOC	PLL Start-up Time (L	.ock Time)	_	20	50	μs		

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typ" column is at 5V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: Limited by oscillator frequency range.

4: Limited by device operating frequency range.

TABLE 20-16: PLL JITTER

АС СНА	RACTERISTICS	Standard Operating Conditions: 2.5V to 5.5V(unless otherwise stated)Operating temperature $-40^{\circ}C \leq TA \leq +85^{\circ}C$ for Industrial $-40^{\circ}C \leq TA \leq +125^{\circ}C$ for Extended						
Param No.	Characteristic	Min	Typ ⁽¹⁾	Max	Units Conditions			
OS61	x4 PLL	—	0.251	0.413	%	-40°C ≤TA ≤+85°C	VDD = 3.0 to 3.6V	
		_	0.251	0.413	%	-40°C ≤TA ≤+125°C	VDD = 3.0 to 3.6V	
		—	0.256	0.47	%	-40°C ≤TA ≤+85°C	VDD = 4.5 to 5.5V	
		_	0.256	0.47	%	-40°C ≤TA ≤+125°C	VDD = 4.5 to 5.5V	
	x8 PLL	_	0.355	0.584	%	-40°C ≤TA ≤+85°C	VDD = 3.0 to 3.6V	
		_	0.355	0.584	%	-40°C ≤TA ≤+125°C	VDD = 3.0 to 3.6V	
		_	0.362	0.664	%	-40°C ≤TA ≤+85°C	VDD = 4.5 to 5.5V	
		_	0.362	0.664	%	-40°C ≤TA ≤+125°C	VDD = 4.5 to 5.5V	
	x16 PLL	_	0.67	0.92	%	-40°C ≤TA ≤+85°C	VDD = 3.0 to 3.6V	
		_	0.632	0.956	%	-40°C ≤TA ≤+85°C	VDD = 4.5 to 5.5V	
		_	0.632	0.956	%	-40°C ≤TA ≤+125°C	VDD = 4.5 to 5.5V	

Note 1: These parameters are characterized but not tested in manufacturing.







TABLE 20-34: I²C[™] BUS DATA TIMING REQUIREMENTS (SLAVE MODE)

AC CHARACTERISTICS			Standard Opera (unless otherwi Operating tempe	ard Operating Conditions: 2.5V to 5.5V so otherwise stated) ting temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended					
Param No.	Symbol	Charact	teristic	Min	Max	Units	Conditions		
IS10	TLO:SCL	Clock Low Time	100 kHz mode	4.7	_	μs	Device must operate at a minimum of 1.5 MHz		
			400 kHz mode	1.3	_	μs	Device must operate at a minimum of 10 MHz.		
			1 MHz mode ⁽¹⁾	0.5	_	μs			
IS11	THI:SCL	Clock High Time	100 kHz mode	4.0		μs	Device must operate at a minimum of 1.5 MHz		
			400 kHz mode	0.6	_	μs	Device must operate at a minimum of 10 MHz		
			1 MHz mode ⁽¹⁾	0.5		μs			
IS20	TF:SCL	SDA and SCL	100 kHz mode	—	300	ns	CB is specified to be from		
		Fall Time	400 kHz mode	20 + 0.1 Св	300	ns	10 to 400 pF		
			1 MHz mode ⁽¹⁾	—	100	ns			
IS21	TR:SCL	SDA and SCL	100 kHz mode	_	1000	ns	CB is specified to be from		
		Rise Time	400 kHz mode	20 + 0.1 Св	300	ns	10 to 400 pF		
			1 MHz mode ⁽¹⁾	_	300	ns			

Note 1: Maximum pin capacitance = 10 pF for all I^2C^{TM} pins (for 1 MHz mode only).



FIGURE 20-21: 12-BIT A/D CONVERSION TIMING CHARACTERISTICS

44-Lead Plastic Quad Flat, No Lead Package (ML) – 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	MILLIMETERS				
Dimensio	MIN	NOM	MAX		
Contact Pitch	0.65 BSC				
Optional Center Pad Width	W2			6.80	
Optional Center Pad Length	T2			6.80	
Contact Pad Spacing	C1		8.00		
Contact Pad Spacing	C2		8.00		
Contact Pad Width (X44)	X1			0.35	
Contact Pad Length (X44)	Y1			0.80	
Distance Between Pads	G	0.25			

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2103A

Worldwide Sales and Service

AMERICAS

Corporate Office 2355 West Chandler Blvd. Chandler, AZ 85224-6199 Tel: 480-792-7200 Fax: 480-792-7277 Technical Support: http://support.microchip.com Web Address: www.microchip.com

Atlanta Duluth, GA Tel: 678-957-9614 Fax: 678-957-1455

Boston Westborough, MA Tel: 774-760-0087 Fax: 774-760-0088

Chicago Itasca, IL Tel: 630-285-0071 Fax: 630-285-0075

Cleveland Independence, OH Tel: 216-447-0464 Fax: 216-447-0643

Dallas Addison, TX Tel: 972-818-7423 Fax: 972-818-2924

Detroit Farmington Hills, MI Tel: 248-538-2250 Fax: 248-538-2260

Kokomo Kokomo, IN Tel: 765-864-8360 Fax: 765-864-8387

Los Angeles Mission Viejo, CA Tel: 949-462-9523 Fax: 949-462-9608

Santa Clara Santa Clara, CA Tel: 408-961-6444 Fax: 408-961-6445

Toronto Mississauga, Ontario, Canada Tel: 905-673-0699 Fax: 905-673-6509

ASIA/PACIFIC

Asia Pacific Office Suites 3707-14, 37th Floor Tower 6, The Gateway Harbour City, Kowloon Hong Kong Tel: 852-2401-1200 Fax: 852-2401-3431 Australia - Sydney

Tel: 61-2-9868-6733 Fax: 61-2-9868-6755

China - Beijing Tel: 86-10-8528-2100 Fax: 86-10-8528-2104

China - Chengdu Tel: 86-28-8665-5511 Fax: 86-28-8665-7889

China - Chongqing Tel: 86-23-8980-9588 Fax: 86-23-8980-9500

China - Hong Kong SAR Tel: 852-2401-1200 Fax: 852-2401-3431

China - Nanjing Tel: 86-25-8473-2460

Fax: 86-25-8473-2470 China - Qingdao Tel: 86-532-8502-7355 Fax: 86-532-8502-7205

China - Shanghai Tel: 86-21-5407-5533 Fax: 86-21-5407-5066

China - Shenyang Tel: 86-24-2334-2829 Fax: 86-24-2334-2393

China - Shenzhen Tel: 86-755-8203-2660 Fax: 86-755-8203-1760

China - Wuhan Tel: 86-27-5980-5300 Fax: 86-27-5980-5118

China - Xian Tel: 86-29-8833-7252 Fax: 86-29-8833-7256

China - Xiamen Tel: 86-592-2388138 Fax: 86-592-2388130

China - Zhuhai Tel: 86-756-3210040 Fax: 86-756-3210049

ASIA/PACIFIC

India - Bangalore Tel: 91-80-3090-4444 Fax: 91-80-3090-4123

India - New Delhi Tel: 91-11-4160-8631 Fax: 91-11-4160-8632

India - Pune Tel: 91-20-2566-1512 Fax: 91-20-2566-1513

Japan - Yokohama Tel: 81-45-471- 6166 Fax: 81-45-471-6122

Korea - Daegu Tel: 82-53-744-4301 Fax: 82-53-744-4302

Korea - Seoul Tel: 82-2-554-7200 Fax: 82-2-558-5932 or 82-2-558-5934

Malaysia - Kuala Lumpur Tel: 60-3-6201-9857 Fax: 60-3-6201-9859

Malaysia - Penang Tel: 60-4-227-8870 Fax: 60-4-227-4068

Philippines - Manila Tel: 63-2-634-9065 Fax: 63-2-634-9069

Singapore Tel: 65-6334-8870 Fax: 65-6334-8850

Taiwan - Hsin Chu Tel: 886-3-6578-300 Fax: 886-3-6578-370

Taiwan - Kaohsiung Tel: 886-7-213-7830 Fax: 886-7-330-9305

Taiwan - Taipei Tel: 886-2-2500-6610 Fax: 886-2-2508-0102

Thailand - Bangkok Tel: 66-2-694-1351 Fax: 66-2-694-1350

EUROPE

Austria - Wels Tel: 43-7242-2244-39 Fax: 43-7242-2244-393 Denmark - Copenhagen Tel: 45-4450-2828 Fax: 45-4485-2829

France - Paris Tel: 33-1-69-53-63-20 Fax: 33-1-69-30-90-79

Germany - Munich Tel: 49-89-627-144-0 Fax: 49-89-627-144-44

Italy - Milan Tel: 39-0331-742611 Fax: 39-0331-466781

Netherlands - Drunen Tel: 31-416-690399 Fax: 31-416-690340

Spain - Madrid Tel: 34-91-708-08-90 Fax: 34-91-708-08-91

UK - Wokingham Tel: 44-118-921-5869 Fax: 44-118-921-5820

08/04/10